

LAMEA Flip Chip Market By Packaging Technology (2.5D IC, 3D IC, and 2D IC), By Bumping Technology (Copper Pillar, Gold Bumping, Solder Bumping and Others), By End User (Electronics, Industrial, IT & Telecom, Automotive, Healthcare & Life Sciences, Aerospace & Defense and Others), By Country, Industry Analysis and Forecast, 2020 - 2026

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Abstracts

The Latin America, Middle East and Africa Flip Chip Market would witness market growth of 10.2% CAGR during the forecast period (2020-2026).

The Flip Chip, also known as the Controlled Collapse Chip Connection (C4), consists of conductive bumps mounted on the sensor pads on the surface of the wafer, accompanied by the mounting of semiconductor devices by flipping the part. The use of flip chip has increased in the electronics industry due to its numerous advantages, such as lower cost, high packaging capacity, improved circuit durability and compact dimensions. As a result, the rise in demand for smart electronics across the globe is a major factor projected to fuel the development of the global market size of the flip chip during the forecast period.

Compared to conventional wire-bond packaging, flip chip offers a variety of advantages, such as superior thermal and electrical efficiency, stability in the substrate for varying performance requirements, remarkable I/O capacity, reduced form factors and well-established process equipment experience. Gold bumping technology contributes the second largest portion of the overall flip chip market. The gold bumping market is projected to see sluggish growth relative to other bumping technologies due to its high production costs, fragile construction, and complexities involved in the bumping phase.

In addition, improved heat dissipation of ball grid style flip chips provides them an acceptable option for applications where smaller size chips are desired without the need for an external heat sink.

The growing in demand for high-speed and portable electronic products has accelerated the adoption of flip chip technology in the electronics industry. The Internet of Things (IoT) has gained attention and is a key driver in the market. Items used in IoT, such as sensors & actuators, analog & mixed-signal translators, and microcontrollers or embedded processors, need effective and reliable packaging solutions that can be produced using flip chips.

Based on Packaging Technology, the market is segmented into 2.5D IC, 3D IC and 2D IC. Based on Bumping Technology, the market is segmented into Copper Pillar, Gold Bumping, Solder Bumping and Others. Based on End User, the market is segmented into Electronics, Industrial, IT & Telecom, Automotive, Healthcare & Life Sciences, Aerospace & Defense and Others. Based on countries, the market is segmented into Brazil, Argentina, UAE, Saudi Arabia, South Africa, Nigeria, and Rest of LAMEA.

The market research report covers the analysis of key stake holders of the market. Key companies profiled in the report include 3M Company, Advanced Micro Devices, Inc., Amkor Technology, Inc., Apple, Inc., Fujitsu Limited, Intel Corporation, IBM Corporation, Samsung Electronics Co., Ltd., Texas Instruments, Inc., and Taiwan Semiconductor Manufacturing Company.

Scope of the Study

Market Segmentation:

By Packaging Technology

2.5D IC

3D IC

2D IC

By Bumping Technology

Copper Pillar

Gold Bumping

Solder Bumping

Others

By End User

Electronics

Industrial

IT & Telecom

Automotive

Healthcare & Life Sciences

Aerospace & Defense

Others

By Country

Brazil

Argentina

UAE

Saudi Arabia

South Africa

Nigeria

Rest of LAMEA

Companies Profiled

3M Company

Advanced Micro Devices, Inc.

Amkor Technology, Inc.

Apple, Inc.

Fujitsu Limited

Intel Corporation

IBM Corporation

Samsung Electronics Co., Ltd.

Texas Instruments, Inc.

Taiwan Semiconductor Manufacturing Company

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